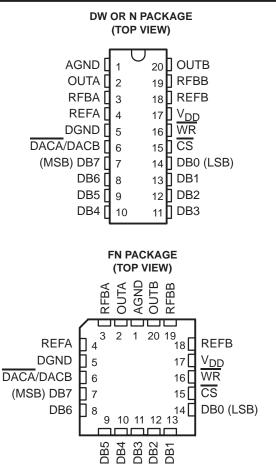
- Easy Microprocessor Interface
- On-Chip Data Latches
- Digital Inputs Are TTL-Compatible With 10.8-V to 15.75-V Power Supply
- Monotonic Over the Entire A/D Conversion Range
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS					
Resolution	8 bits				
Linearity Error	1/2 LSB				
Power Dissipation	20 mW				
Settling Time	100 ns				
Propagation Delay Time	80 ns				

description

The TLC7628C, TLC7628E, and TLC7628I are dual, 8-bit, digital-to-analog converters (DACs) designed with separate on-chip data latches and feature exceptionally close DAC-to-DAC matching. Data is transferred to either of the two DAC data latches through a common, 8-bit input port. Control input DACA/DACB determines which DAC is loaded. The load cycle of these devices is similar to the write cycle of a random-access memory, allowing easy interface



to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

The TLC7628C operates from a 10.8-V to 15.75-V power supply and is TTL-compatible over this range. 2- or 4-quadrant multiplying makes these devices a sound choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7628C is characterized for operation from 0°C to 70°C. The TLC7628I is characterized for operation from –25°C to 85°C. The TLC7628E is characterized for operation from –40°C to 85°C.

AVAILABLE OPTIONS

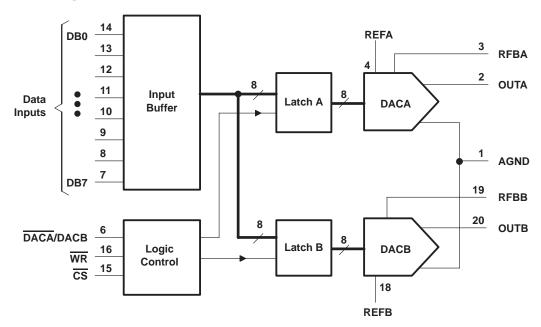
	PACKAGE				
TA	SMALL OUTLINE PLASTIC DIP (DW)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)		
0°C to 70°C	TLC7628CDW	TLC7628CFN	TLC7628CN		
-25°C to 85°C	TLC7628IDW	TLC7628IFN	TLC7628IN		
-40°C to 85°C	TLC7628EDW	TLC7628EFN	TLC7628EN		



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

(Supply voltage range, V _{DD} (to AGND or DGND)	–0.3 V to 17 V
١	/oltage between AGND and DGND	V _{DD}
I	nput voltage range, V _I (to DGND)	. $-0.3 \text{ V to V}_{DD} + 0.3 \text{ V}$
F	Reference voltage range, V _{refA} or V _{refB} (to AGND)	±25 V
F	Feedback voltage range, V _{RFBA} or V _{RFBB} (to AGND)	±25 V
(Output voltage range, VOA or VOB (to AGND)	±25 V
F	Peak input current	10 μΑ
(Operating free-air temperature range, T _A : TLC7628C	0°C to 70°C
	TLC7628I	
	TLC7628E	40°C to 85°C
5	Storage temperature range, T _{stg}	65°C to 150°C
	Case temperature for 10 seconds, T _C : FN package	
Į	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	Supply voltage, V _{DD}				15.75	V
Reference voltage, V _{refA} or V _{refB}				±10		V
High-level input voltage, VIH			2.4			V
Low-level input voltage, V _{IL}					0.8	V
CS setup time, t _{SU(CS)}			50			ns
CS hold time, th(CS) (see Figure 1)						ns
DAC select setup time, t _{Su(DAC)} (see Figure 1)			60			ns
DAC select hold time, t _{h(DAC)} (see Figure 1)			10			ns
Data bus input setup time t _{SU(D)} (see Figure 1)			25			ns
Data bus input hold time th(D) (see Figure 1)			10			ns
Pulse duration, WR low, t _{W(WR)} (see Figure 1)			50			ns
	TLC7628C		0		70	
Operating free-air temperature, TA	TLC7628I		-25		85	°C
	TLC7628E		-40		85	

electrical characteristics over recommended ranges of operating free-air temperature and V_{DD} , $V_{refA} = V_{refB} = 10 \text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

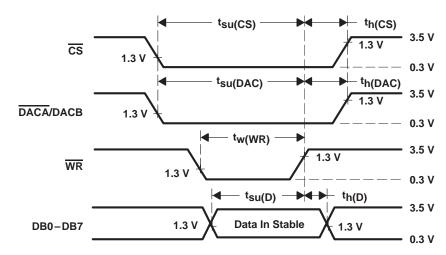
PARAMETER			TEST CONDITIONS			MAX	UNIT	
I	IH High-level input current		M. M	Full range		10	^	
ЧH			$V_I = V_{DD}$	25°C		1	μΑ	
1	Low-level input current		V _I = 0	Full range		-10		
ΙΙL	Low-level input current		V = 0	25°C		-1	μΑ	
	Reference input impedance R AGND	EFA or REFB to			5	20	kΩ	
		OUTA	DAC data latch loaded with 00000000,	Full range		±200		
A Contract land and a comment	Output lookogo gurront	$V_{refA} = \pm 10 V$	$V_{refA} = \pm 10 \text{ V}$	25°C		±50	nA	
чкg	lkg Output leakage current	OUTB	DAC data latch loaded with 00000000, $V_{refB} = \pm 10 \text{ V}$	Full range		±200		
		ООТВ		25°C		±50		
Input resistance match (REFA to REFB)					±1%			
	DC supply sensitivity ∆gain/∆V _{DD}		$\Delta V_{DD} = \pm 5 \%$	Full range		0.02	%/%	
	Do supply sensitivity again/av	עס"	A DD = 7.3 %	25°C		0.01	707 70	
		Quiescent	All digital inputs at VIHmin or VILmax			2		
I_{DD}	Supply current	Supply current	All digital inputs at 0 V or VDD	Full range		0.5	mA	
		Stariuby	Standby All digital inputs at 0 V or V _{DD}			0.1		
		DB0-DB7				10		
Ci	C _i Input capacitance WR, CS					15	pF	
O Outrat agree (ALTA OUTR)		DAC data latches loaded with 00000000			25	ne.		
0	C _O Output capacitance (OUTA, OUTB)		DAC data latches loaded with 11111111			60	pF	



operating characteristics over recommended ranges of operating free-air temperature and VDD, $V_{refA} = V_{refB} = 10 \text{ V}, V_{OA} \text{ and } V_{OB} \text{ at } 0 \text{ V} \text{ (unless otherwise noted)}$

PARAN	IETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	
Linearity error						±1/2	LSB	
Settling time (to 1/2 L	_SB)	See Note 1				100	ns	
		Con Note 2	Full range			±3	LSB	
Gain error		See Note 2	25°C			±2	LSB	
AC foodthrough	REFA to OUTA	Con Note 2	Full range			-65		
AC feedthrough	REFB to OUTB	See Note 3	25°C			-75	dB	
Temperature coefficient of gain				±0.0035	%FSR/°C			
Propagation delay (fr 90% of final analog of		See Note 4				80	ns	
Channel-to-channel	REFA to OUTB	See Note 5	25°C		80		-10	
isolation	REFB to OUTA	See Note 6	See Note 6 25°C		80		dB	
Digital-to-analog glito	Measured for code transition from 00000000 to 11111111, $T_A = 25$ °C			330		nV∙s		
Digital crosstalk		Measured for code transition from 00000000 to 111111111, $T_A = 25^{\circ}C$			60		nV∙s	
Harmonic distortion		$V_i = 6 \text{ V}, f = 1 \text{ kHz}, T_A = 25^{\circ}\text{C}$		$V_i = 6 \text{ V}, f = 1 \text{ kHz}, T_A = 25^{\circ}\text{C}$ -85		-85		dB

- 1. OUTA, OUTB load = 100 Ω , C_{ext} = 13 pF; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at $\overline{0}$ V to V_{DD} or V_{DD} to 0 V. NOTES:
 - 2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = V_{ref} 1 LSB. Both DAC latches are loaded with 11111111.
 - 3. V_{ref} = 20 V peak-to-peak, 10-kHz sine wave
 - 4. $V_{refA} = V_{refB} = 10 \text{ V}$; OUTA/OUTB load = 100Ω , $C_{ext} = 13 \text{ pF}$; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
 - 5. $V_{refA} = 20 \text{ V peak-to-peak}$, 10-kHz sine wave; $V_{refB} = 0$
 - 6. V_{refB} = 20 V peak-to-peak, 10-kHz sine wave; V_{refA} = 0



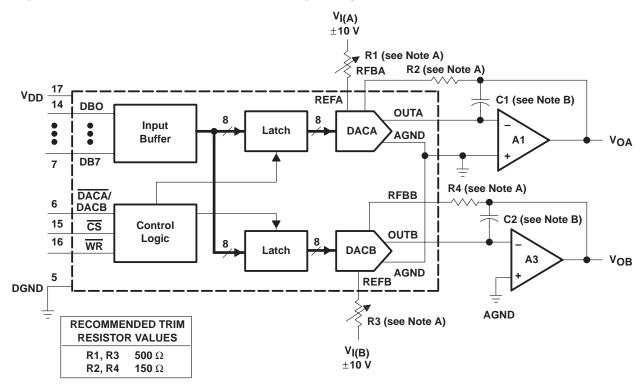
For all input signals, $t_r = t_f = 5$ ns (10% to 90% points).

Figure 1. Setup and Hold Times



APPLICATION INFORMATION

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 2 and 3, respectively.

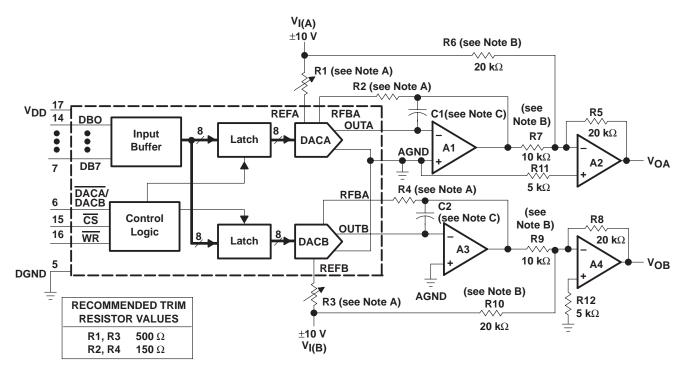


- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
 - B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 2. Unipolar Operation (2-Quadrant Multiplication)

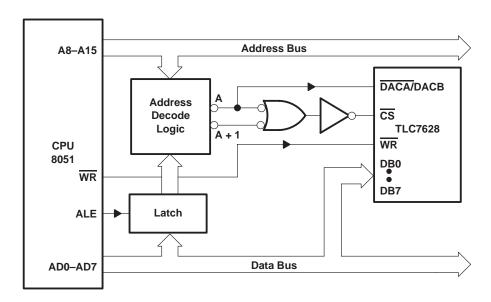


APPLICATION INFORMATION



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Adjust R1 for VOA = 0 V with code 10000000 in DACA latch. Adjust R3 for VOB = 0 V with 10000000 in DACB latch.
 - B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
 - C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

Figure 3. Bipolar Operation (4-Quadrant Operation)

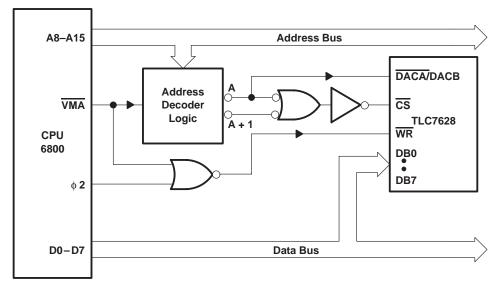


NOTE D: A = decoded address for TLC7628 DACA A + 1 = decoded address for TLC7628 DACB

Figure 4. TLC7628 — Intel 8051 Interface



APPLICATION INFORMATION



NOTE D: A = decoded address for TLC7628 DACA A + 1 = decoded address for TLC7628 DACB

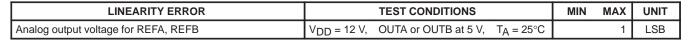
Figure 5. TLC7628 - 6800 Interface

voltage-mode operation

The current-multiplying DAC in these devices can be operated in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. An example of a current-multiplying DAC operating in voltage mode is shown in Figure 6. The relationship between the fixed input voltage and the analog output voltage is given by the following equation:

Analog output voltage = fixed input voltage (D/256)

where D = the digital input. In voltage-mode operation, these devices meet the following specification:



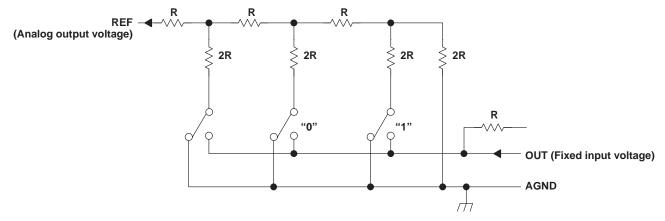


Figure 6. Current-Multiplying DAC Operating in Voltage Mode



PRINCIPLES OF OPERATION

These devices contain two, identical, 8-bit, multiplying DACs: DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between the DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA or DACB with all digital inputs low is shown in Figure 7.

Figure 8 shows the DACA or DACB equivalent circuit. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. The C_0 is caused by the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_0 is 25 pF to 60 pF maximum. The equivalent output resistance (I_0) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

These devices interface to a microprocessor through the data bus, \overline{CS} , \overline{WR} , and $\overline{DACA}/DACB$ control signals. When \overline{CS} and \overline{WR} are both low, the analog output on these devices, specified by the $\overline{DACA}/DACB$ control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs is latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled, regardless of the state of the \overline{WR} signal.

The digital inputs of these devices provide TTL compatibility when operated from a supply voltage of 10.8 V to 15.75 V.

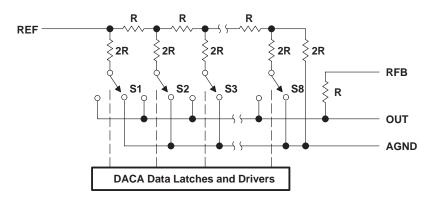


Figure 7. Simplified Functional Circuit for DACA or DACB

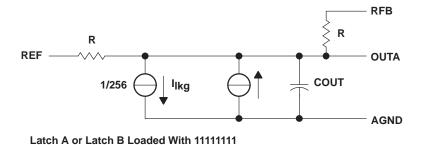


Figure 8. TLC7628 Equivalent Circuit for DACA or DACB



PRINCIPLES OF OPERATION

Table 1. Mode Selection Table

DACA/DACB	CS	WR	DACA	DACB
L	L	L	Write	Hold
Н	L	L	Hold	Write
X	Н	Х	Hold	Hold
X	Х	Н	Hold	Hold

L = low level, H = high level, X = don't care

Table 2. Unipolar Binary Code

DAC LATCH CONTENTS (see Note 7)	ANALOG OUTPUT				
MSB LSB					
1111111 1000001 1000000 0111111 00000001	-V _I (255/256) -V _I (129/256) -V _I (128/256) = -V _I /2 -V _I (127/256) -V _I (1/256) -V _I (0/256) = 0				

Table 3. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS (see Note 8)	ANALOG OUTPUT
MSB LSB	
11111111	V _I (127/128)
1000001	V _I (1/128)
1000000	0 V
0111111	−V _I (1/128)
0000001	-V _I (127/128)
0000000	-V _I (128/128)

NOTES: 7. $1 LSB = (2^{-8})V_{\parallel}$ 8. $1 LSB = (2^{-7})V_{\parallel}$



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